



University Mobility in Asia and the Pacific (UMAP) International Secretariat

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To: Coordinators who plan to apply for UMAP Programs A&B 2018-2 (for Spring Semester 2019)

From: UMAP International Secretariat

Re: Application instructions

We are pleased to announce instructions on how to apply for Programs A&B 2018-2 (Spring 2019) to be offered by member institutions of UMAP.

If your students are interested in participating in one of these programs, please review the information on the website (http://umap.org/programs/a_b/) and advise them about the programs' contents, length, available credits, and fees before applying.

The common application form for Programs A&B is available on the UMAP website (<http://umap.org/forstudents/#application-procedure>). The application deadline for the first cycle is 25 July and for the second cycle is 26 September 2018.

To apply, the following **two steps need to be completed**:

- APPLICATION -- **Students** complete the Application Form for the desired program in **WORD** format and submit it to the UMAP coordinator at their home university/institution.

Coordinators collect the submitted applications and send them all together to the UMAP International Secretariat by email at umap-is@umap.org

- REGISTRATION -- **Coordinators** register the information on each application at the following URL:
https://docs.google.com/forms/d/e/1FAIpQLSe_VbsK4eNJaLSVoH9onRN2h7K1hrCF64tGraB18RZHKX7cBw/viewform

Please note;

1. Only those universities/institutions that have sent the "Outline of Proposal" for participation in this program are able to send their students to the other participating universities/institutions.
2. A maximum of two (2) students can be nominated from each university/institution per semester, but it may be possible to nominate additional students on a fee-paying basis depending on the policies of the host institutions.

We look forward to receiving many applications.